



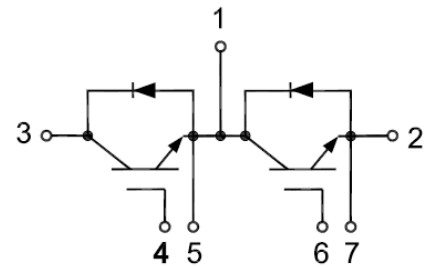
SYMF75HF120T1VH

IGBT Module

Features:

- Non Punch Through (NPT) Technology
- Short Circuit Rated >10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested ($2 \times I_c$)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

Circuit Diagram



Applications:

- Welding Machine、Cutting Machine
- Plating Power Supply、Induction Heating
- SMPS、UPS

IGBT, Inverter

Maximum Rated Values of IGBT($T_C=25^\circ\text{C}$ unless otherwise specified)

V_{CES}	Collector-Emitter Blocking Voltage		1200	V
V_{GES}	Gate-Emitter Voltage		± 20	V
I_c	Continuous Collector Current	$T_C = 100^\circ\text{C}$	75	A
		$T_C = 25^\circ\text{C}$	150	A
I_{CM}	Repetitive Peak Collector Current	$T_J = 150^\circ\text{C}$	150	A
t_{sc}	Short Circuit Withstand Time		>10	μs
P_D	Maximum Power Dissipation per IGBT	$T_C = 25^\circ\text{C}$ $T_{Jmax} = 150^\circ\text{C}$	735	W

Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 2\text{mA}, V_{CE} = V_{GE}$	5.0	5.7	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 75\text{A}, V_{GE} = 15\text{V}$	$T_J = 25^\circ\text{C}$	3.25		V
			$T_J = 125^\circ\text{C}$	4.05		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_J = 25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}, T_J = 25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 100\text{KHz}$		6.70		nF
C_{oes}	Output Capacitance			0.62		nF
C_{res}	Reverse Transfer Capacitance			0.27		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	635	ns
			$T_J = 125^\circ\text{C}$	615	
t_r	Rise Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	125	ns
			$T_J = 125^\circ\text{C}$	120	
$t_{d(off)}$	Turn-off Delay Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	615	ns
			$T_J = 125^\circ\text{C}$	620	
t_f	Fall Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	150	ns
			$T_J = 125^\circ\text{C}$	175	
E_{on}	Turn-on Switching Loss	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ $di/dt = 520\text{A}/\mu\text{s} (T_J = 125^\circ\text{C}),$ Inductive Load	$T_J = 25^\circ\text{C}$	6.2	mJ
			$T_J = 125^\circ\text{C}$	7.7	
E_{off}	Turn-off Switching Loss	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 13.6\Omega, V_{GE} = \pm 15\text{V},$ $du/dt = 4140\text{V}/\mu\text{s} (T_J = 125^\circ\text{C}),$ Inductive Load	$T_J = 25^\circ\text{C}$	3.6	mJ
			$T_J = 125^\circ\text{C}$	4.8	
Q_g	Total Gate Charge	$V_{GE} = +15\text{V} \dots -15\text{V}$	$T_J = 25^\circ\text{C}$	0.9	μC
RBSOA	Reverse Bias Safe Operation Area	$I_C = 150\text{A}, V_{CC} = 1050\text{V}, V_p = 1200\text{V},$ $R_{Goff} = 13.6\Omega, V_{GE} = +15\text{V to } 0\text{V}, T_J = 125^\circ\text{C}$	Trapezoid		
SCSOA	SCSOA	$V_{CC} = 600\text{V}, V_{GE} = 15\text{V},$ $T_J = 150^\circ\text{C}$	10		μs
$R_{\theta JC}$	IGBT Thermal Resistance: Junction-To-Case (per IGBT)			0.17	$^\circ\text{C}/\text{W}$



Diode, Inverter

Maximum Rated Values of Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	75	A
I_{FM}	Diode Maximum Forward Current	150	A

Electrical Characteristics of Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit	
V_{FM}	Forward Voltage	$I_F = 75\text{A}$	$T_J=25^\circ\text{C}$		2.40	V	
			$T_J=125^\circ\text{C}$		2.50		
t_{rr}	Reverse Recovery Time	$I_F=75\text{A},$ $-di_F/dt = 770\text{A}/\mu\text{s}(T_J=125^\circ\text{C}),$ $V_{rr} = 600\text{V},$ $V_{GE} = -15\text{V}$	$T_J=25^\circ\text{C}$		170	ns	
			$T_J=125^\circ\text{C}$		360		
I_{rr}	Peak Reverse Recovery Current		$T_J=25^\circ\text{C}$		32.8	A	
			$T_J=125^\circ\text{C}$		45.3		
Q_{rr}	Reverse Recovery Charge		$T_J=25^\circ\text{C}$		3.27	μC	
			$T_J=125^\circ\text{C}$		7.35		
E_{rec}	Reverse Recovery Energy		$T_J=25^\circ\text{C}$		0.98	mJ	
			$T_J=125^\circ\text{C}$		2.58		
$R_{\theta JC}$	Diode Thermal Resistance: Junction-To-Case(per Diode)				0.50	$^\circ\text{C}/\text{W}$	



Module

Symbol	Description	Min	Typ	Max	Unit
V _{iso}	Isolation Voltage (All Terminals Shorted)	f = 50Hz, 30s	4500		V
T _J	Maximum Junction Temperature			150	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+150	°C
T _{stg}	Storage Temperature	-40		+125	°C
CTI	Comparative Tracking Index	200			V
R _{ecs}	Case-To-Sink Thermally (Conductive Grease Applied)			0.07	°C/W
T	Power Terminals Screw:M5	3.0		5.0	N·m
T	Mounting Screw:M6	4.0		6.0	N·m
G	Weight		165		g

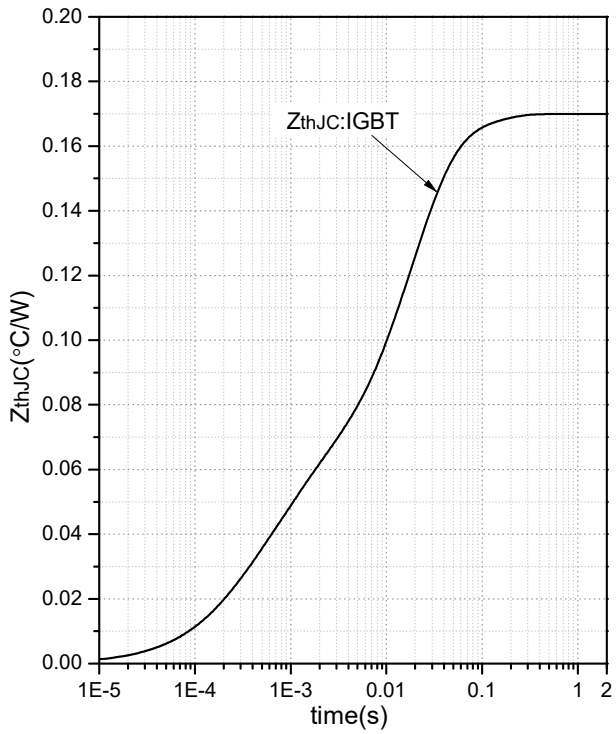


Fig.1 Transient Thermal Impedance (IGBT)

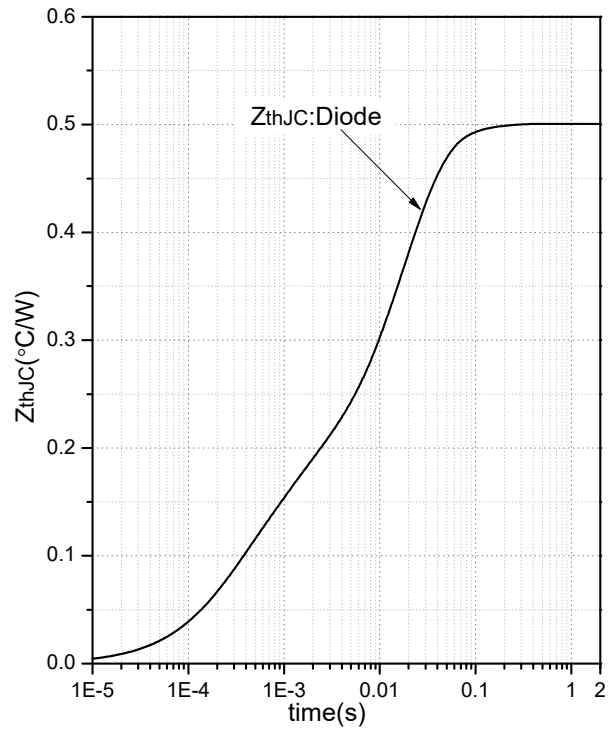


Fig.2 Transient Thermal Impedance (Diode)

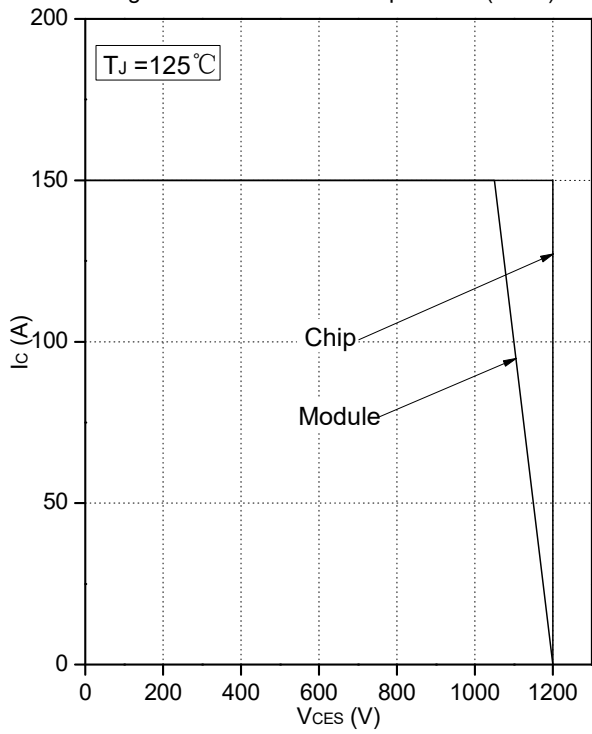


Fig.3 Reverse Bias Safe Operation Area (RBSOA)

